


## Features

- $BV_{CEO} > -80V$
- $I_C = -1A$  High Continuous Collector Current
- $I_{CM} = -2A$  Peak Pulse Current
- 520mW Power Dissipation
- Low Saturation Voltage  $V_{CE(sat)} < -500mV$  @  $-0.5A$
- Complementary NPN Type: BC56-16PA
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

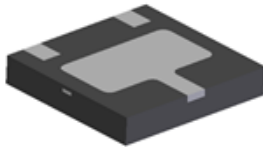
## Mechanical Data

- Case: U-DFN2020-3 (Type B)
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 
- Weight: 0.01 grams (Approximate)

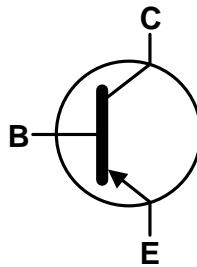
## Applications

- Medium Power Switching or Amplification Applications
- AF Driver and Output Stages

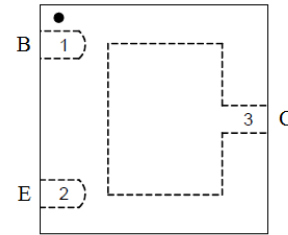
U-DFN2020-3 (Type B)



Bottom View



Device Symbol



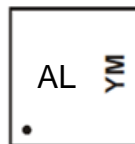
Top View  
Pin-Out

## Ordering Information (Note 4)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
BC53-16PA-7	AEC-Q101	AL	7	12	3,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



AL = Product Type Marking Code  
YM = Date Code Marking  
Y = Year (ex: C = 2015)  
M = Month (ex: 9 = September)

### Date Code Key

Year	2015	2016	2017	2018	2019	2020	2021	2022				
Code	C	D	E	F	G	H	I	J				
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-100	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-80	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	I <sub>C</sub>	-1	A
Peak Pulse Collector Current	I <sub>CM</sub>	-2	
Continuous Base Current	I <sub>B</sub>	-100	mA
Peak Pulse Base Current	I <sub>BM</sub>	-200	

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

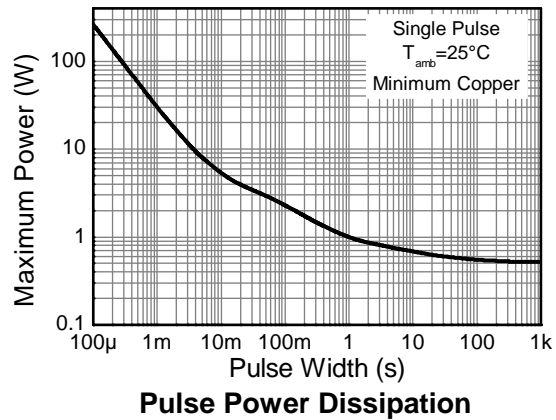
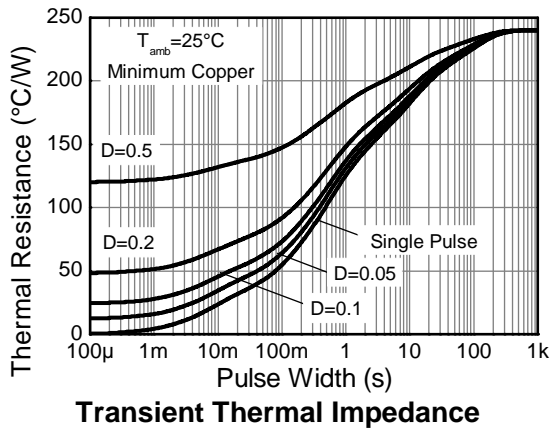
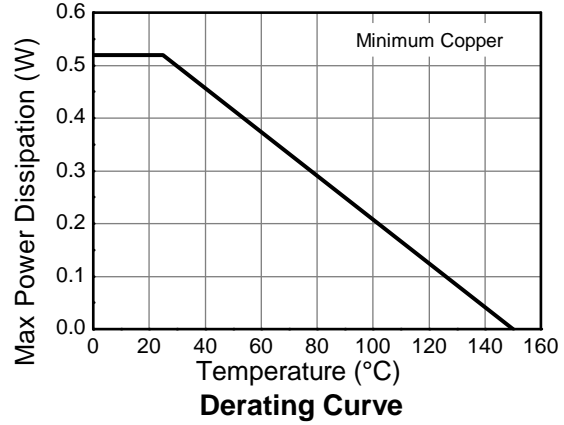
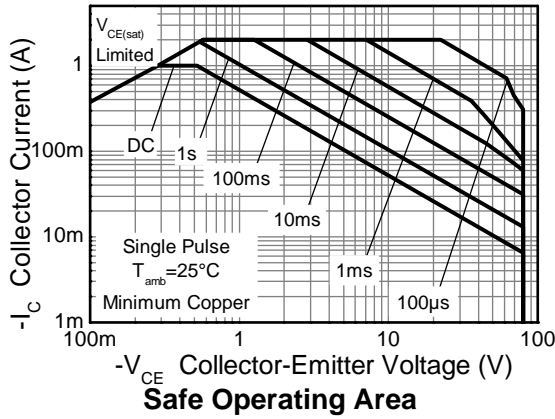
Characteristic	Symbol	Value	Unit
Power Dissipation	(Note 5) P <sub>D</sub>	520	mW
Thermal Resistance, Junction to Ambient	(Note 5) R <sub>θJA</sub>	240	°C/W
Thermal Resistance, Junction to Leads	(Note 6) R <sub>θJL</sub>	20	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**ESD Ratings** (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted on minimum recommended pad layout FR4 PCB single sided 1oz copper; device is measured under still air conditions while operating in a steady-state.
  6. Thermal resistance from junction to solder-point (at the end of the collector lead).
  7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

**Thermal Characteristics and Derating Information**



**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-100	-	-	V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage (Note 8)	BV <sub>CEO</sub>	-80	-	-	V	I <sub>C</sub> = -10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	-	-	V	I <sub>E</sub> = -100μA
Collector Cut-off Current	I <sub>CBO</sub>	-	-	-0.1 -20	μA	V <sub>CB</sub> = -30V V <sub>CB</sub> = -30V, T <sub>A</sub> = +150°C
Emitter Cut-off Current	I <sub>EBO</sub>	-	-	-20	nA	V <sub>EB</sub> = -4V
Static Forward Current Transfer Ratio (Note 8)	h <sub>FE</sub>	25 100 25	- - -	- 250 -	-	I <sub>C</sub> = -5mA, V <sub>CE</sub> = -2V I <sub>C</sub> = -150mA, V <sub>CE</sub> = -2V I <sub>C</sub> = -500mA, V <sub>CE</sub> = -2V
Collector-Emitter Saturation Voltage (Note 8)	V <sub>CE(sat)</sub>	-	-	-0.5	V	I <sub>C</sub> = -500mA, I <sub>B</sub> = -50mA
Base-Emitter Turn-On Voltage (Note 8)	V <sub>BE(on)</sub>	-	-	-1.0	V	I <sub>C</sub> = -500mA, V <sub>CE</sub> = -2V
Transition Frequency	f <sub>T</sub>	-	125	-	MHz	I <sub>C</sub> = -50mA, V <sub>CE</sub> = -10V f = 100MHz
Output Capacitance	C <sub>obo</sub>	-	-	25	pF	V <sub>CB</sub> = -10V, f = 1MHz

Note: 8. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

**Typical Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

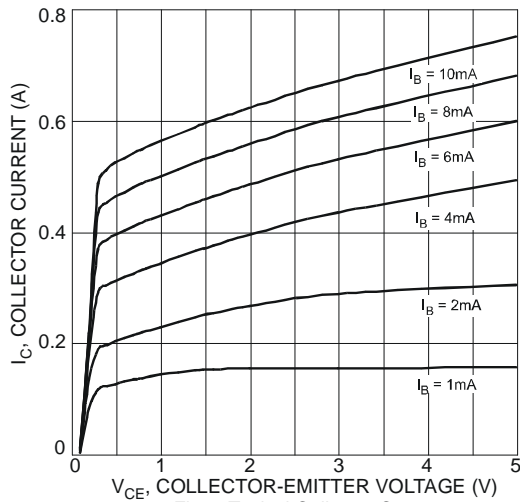


Fig. 1 Typical Collector Current vs. Collector-Emitter Voltage

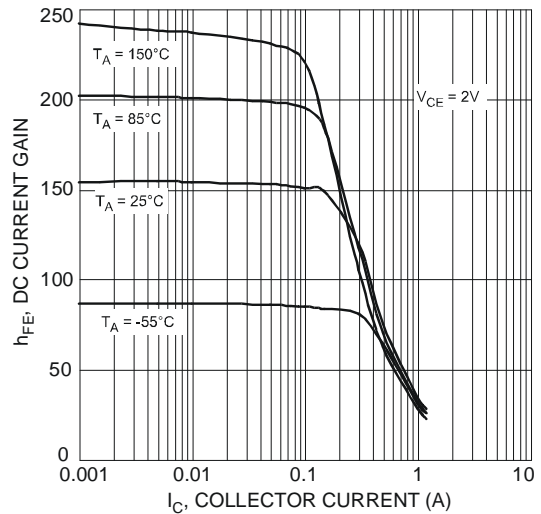


Fig. 2 Typical DC Current Gain vs. Collector Current

**Typical Electrical Characteristics** (continued)

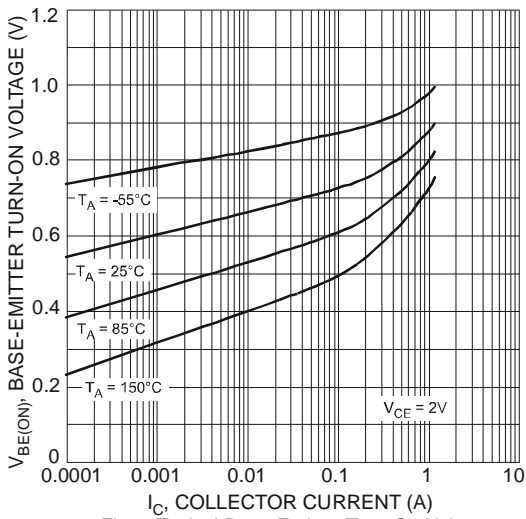


Fig. 3 Typical Base-Emitter Turn-On Voltage vs. Collector Current

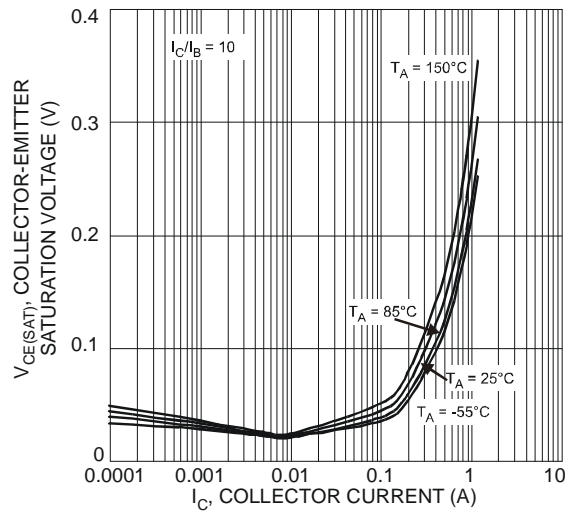


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

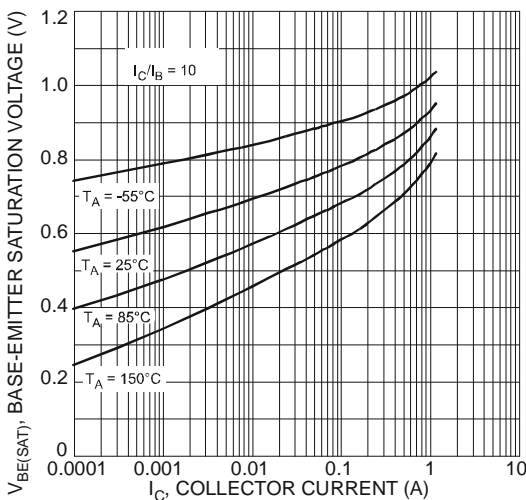


Fig. 5 Typical Base-Emitter Saturation Voltage vs. Collector Current

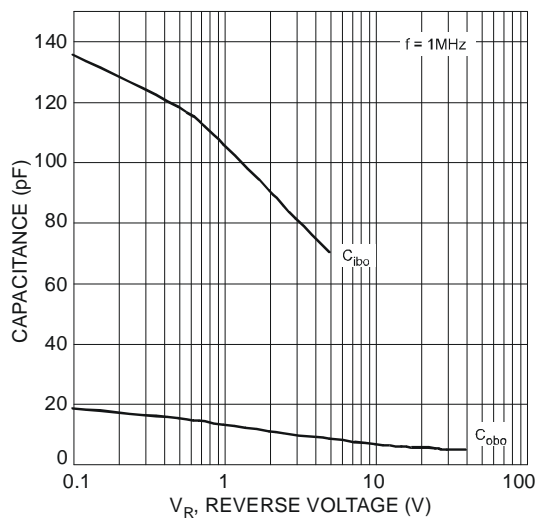
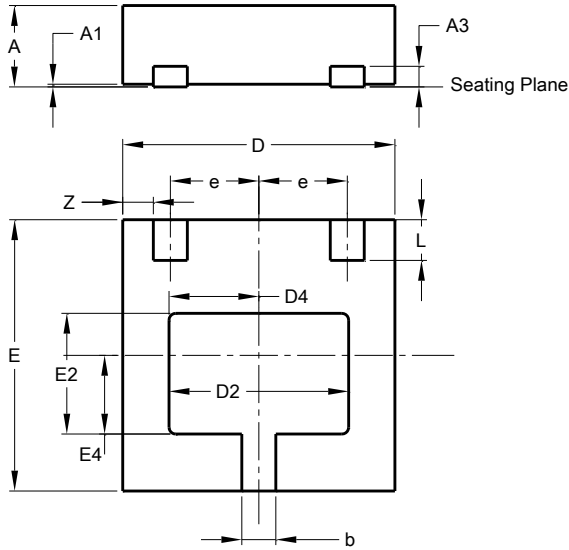


Fig. 6 Typical Capacitance Characteristics

**Package Outline Dimensions**

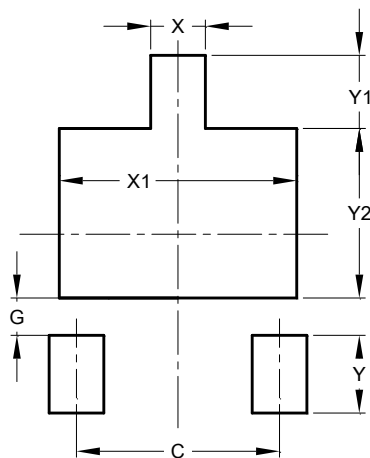
Please see AP02001 at [http://www.diodes.com/\\_files/datasheets/ap02001.pdf](http://www.diodes.com/_files/datasheets/ap02001.pdf) for the latest version.



U-DFN2020-3 (Type B)			
Dim	Min	Max	Typ
A	0.57	0.63	0.60
A1	0.00	0.05	0.02
A3	—	—	0.152
b	0.20	0.30	0.25
D	1.950	2.075	2.00
D2	1.22	1.42	1.32
D4	0.56	0.76	0.66
E	1.950	2.075	2.00
E2	0.79	0.99	0.89
E4	0.48	0.68	0.58
e	—	—	0.65
L	0.25	0.35	0.30
Z	—	—	0.225
All Dimensions in mm			

**Suggested Pad Layout**

Please see AP02001 at [http://www.diodes.com/\\_files/datasheets/ap02001.pdf](http://www.diodes.com/_files/datasheets/ap02001.pdf) for the latest version.



Dimensions	Value (in mm)
C	1.300
G	0.240
X	0.350
X1	1.520
X2	1.700
Y	0.500
Y1	0.470
Y2	1.090

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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